

PROCESS AND APPARATUS FOR FORMING OXIDE FILM, AND
ELECTRONIC DEVICE MATERIAL

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ABSTRACT OF THE DISCLOSURE

An oxide film-forming apparatus, comprising: a
10 process chamber for disposing an electronic device
substrate at a predetermined position; water vapor supply
means for supplying water vapor into the process chamber;
and plasma exciting means for activating the water vapor
with plasma, whereby the surface of the electronic device
15 substrate can be irradiated with the plasma based on the
water vapor.